

**REMARKS**

Claims 1-17 are pending in the above-identified application. Claims 1-17 were rejected. With this amendment, claims 1, 2, 5, 6, 11, 13, and 15 were amended. Claim 10 was cancelled. Applicant maintains that no new matter has been added with this amendment. Accordingly, claims 1-9, and 11-17 are at issue in the above-identification application.

Claims 1-9 and 11-17 were rejected under 35 U.S.C. §112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which Applicant regards as the invention. In response, Applicant has amended claim 1 and substituted the term “elements” for the term “devices.” With regards to claim 5, Applicant respectfully disagrees with the Examiner and feels that the term film-like was disclosed in the specification on Page 33 and in Fig. 10. Therefore, Applicant does not feel that claim 5 is vague and indefinite. Applicant has also amended claim 2 to change the term “second period” to just “period.” Applicant has also amended claims 11, 13 and 15 to remove the term “individually separated.” Claims 11, 13 and 15 have also been amended to delete the term “mounting” and replace it with the term “separating” in the preamble. Applicant maintains, that as a result of the amendments made and the arguments made above, that this rejection should be withdrawn.

Claims 1, 2, 4, 7-12, 15, and 17 were rejected under 35 U.S.C. § 102(b) as being anticipated by *Tetsuo et al.* (JP application number 1979-91683). Amended claim 1, from which claims 2-9 depend, recites a method for mounting a plurality of elements comprising separating a plurality of elements, which are *two-dimensionally formed* and arrayed at a first period on a substrate, into individual elements while keeping the first period as it is, wherein more than one but not all of the elements in a given row are separated from the substrate. Additionally, amended claims 11, 13 and 15 recite a method for separating a plurality of elements comprising

separating a plurality of elements arrayed on a substrate from the substrate, wherein the elements have been *two-dimensionally formed* and arrayed on the substrate at a first period. *Tetsuo et al.* fails to fairly teach or suggest this method. In contrast *Tetsuo et al.* teaches a plurality of devices which are one-dimensionally formed on a substrate.

Claims 10 and 13-17 were rejected under 35 U.S.C. § 102(b) as being anticipated by *Zavracky et al.* (U.S. Patent No. 5,206,749). Applicant respectfully traverse this rejection. Applicant has cancelled claim 10, and therefore claim 10 is no longer at issue. Claims 13 and 15 both recite handling elements so as to re-array the elements separated from the substrate at a *second period* equivalent to a *multiple of the first period*. *Zavracky et al.* does not teach nor suggest re-arraying elements separated from a substrate at a second period equivalent to a *multiple of the first period*. What *Zavracky et al.* does disclose is transferring an array of transistors or thin film semiconductor regions on to a stretchable substrate 302, and then stretching the substrate along an axis 306, as shown in Fig. 13b. The substrate 302 is then stretched along an axis 314 to produce the array shown in Fig. 13c. (See *Zavracky et al.*, column 14, lines 47-54). *Zavracky et al.* fails to teach or disclose that the distance 308 between devices 304 or that the spacing 312 result in a structure in which the elements are separated from the substrate at a second period equivalent to a *multiple of the first period*. Accordingly, Applicant submits that the claimed invention is not anticipated by nor obvious over the applied references, either alone or in combination. Withdrawal of these grounds of rejection is respectfully requested. In view of the foregoing, Applicant submits that the application is in condition for allowance. Notice to that effect is requested.

Respectfully submitted,

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A handwritten signature in black ink, appearing to read 'DR', is written over a horizontal line.

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